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Oct. 22, 2008

To: Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
 28 Davis Avenue  
 Poughkeepsie, N.Y. 12603

Subject:	Serial No. 10/786,807	Feb. 25, 2004
	H. M. CHEN ET AL.	
	“METHOD FOR IMPROVING SEMICONDUCTOR WAFER TEST ACCURACY”	
	Grp. Art Unit: 2822	AU, BAC-H

## RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

In response to the Non-Final Office Action mailed July 24, 2008, please amend the above-identified application for patent and consider the remarks, as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Oct. 24, 2008.

Cathleen M. Stanton

Signature Cathleen M. Stanton  
 Date October 24, 2008

**Amendments to the Claims** are reflected in the listing of the Claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.